

MOS FIELD EFFECT TRANSISTOR

NP80N04CHE,NP80N04DHE,NP80N04EHE,NP80N04KHE

SWITCHING N-CHANNEL POWER MOS FET

DESCRIPTION

These products are N-channel MOS Field Effect
Transistor designed for high current switching applications.

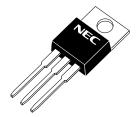
FEATURES

- Channel temperature 175 degree rated
- Super low on-state resistance $R_{DS(on)} = 8.0 \ m\Omega$ MAX. (Vgs = 10 V, lb = 40 A)
- Low Ciss : Ciss = 2200 pF TYP.
- Built-in gate protection diode

ORDERING INFORMATION

PART NUMBER	PACKAGE
NP80N04CHE	TO-220AB
NP80N04DHE	TO-262
NP80N04EHE	TO-263 (MP-25ZJ)
NP80N04KHE	TO-263 (MP-25ZK)

(TO-220AB)



(TO-262)



(TO-263)



ABSOLUTE MAXIMUM RATINGS ($T_A = 25$ °C)

Drain to Source Voltage (Vgs = 0 V)	Voss	40	V
Gate to Source Voltage (Vps = 0 V)	Vgss	±20	V
Drain Current (DC) Note1	ID(DC)	±80	Α
Drain Current (Pulse) Note2	ID(pulse)	±280	Α
Total Power Dissipation (T _A = 25°C)	Рт	1.8	W
Total Power Dissipation (Tc = 25°C)	Рт	120	W
Channel Temperature	Tch	175	°C
Storage Temperature	Tstg	-55 to +175	°C
Single Avalanche Current Note3	las	52 / 31 / 13	Α
Single Avalanche Energy Note3	Eas	2.7 / 96 / 169	mJ

Notes 1. Calculated constant current according to MAX. allowable channel temperature.

- **2.** PW \leq 10 μ s, Duty cycle \leq 1%
- **3.** Starting T_{ch} = 25°C, R_G = 25 Ω , V_{GS} = 20 \rightarrow 0 V (See Figure 4.)

THERMAL RESISTANCE

Channel to Case Thermal Resistance	Rth(ch-C)	1.25	°C/W
Channel to Ambient Thermal Resistance	Rth(ch-A)	83.3	°C/W

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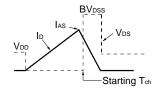


ELECTRICAL CHARACTERISTICS (TA = 25°C)

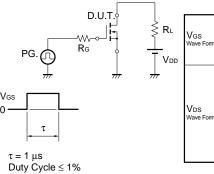
Characteristics	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Zero Gate Voltage Drain Current	IDSS	V _{DS} = 40 V, V _{GS} = 0 V			10	μΑ
Gate to Source Leakage Current	Igss	Vgs = ±20 V, Vps = 0 V			±10	μΑ
Gate to Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	2.0	3.0	4.0	>
Forward Transfer Admittance	y _{fs}	V _{DS} = 10 V, I _D = 40 A	15	31		Ø
Drain to Source On-state Resistance	RDS(on)	Vgs = 10 V, ID = 40 A		6.2	8.0	mΩ
Input Capacitance	Ciss	V _{DS} = 25 V		2200	3300	pF
Output Capacitance	Coss	Vgs = 0 V		490	730	pF
Reverse Transfer Capacitance	Crss	f = 1 MHz		230	410	pF
Turn-on Delay Time	td(on)	V _{DD} = 20 V, I _D = 40 A		24	52	ns
Rise Time	tr	Vgs = 10 V		14	36	ns
Turn-off Delay Time	t _{d(off)}	R _G = 1 Ω		44	88	ns
Fall Time	t _f			15	37	ns
Total Gate Charge	QG	V _{DD} = 32 V		40	60	nC
Gate to Source Charge	Qgs	Vgs = 10 V		12		nC
Gate to Drain Charge	Q _{GD}	ID = 80 A		16		nC
Body Diode Forward Voltage	V _F (S-D)	IF = 80 A, VGS = 0 V		1.0		V
Reverse Recovery Time	trr	IF = 80 A, VGS = 0 V		40		ns
Reverse Recovery Charge	Qrr	di/dt = 100 A/μs		50		nC

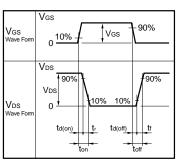
TEST CIRCUIT 1 AVALANCHE CAPABILITY

$\begin{array}{c} \text{D.U.T.} \\ \text{RG} = 25 \ \Omega \\ \text{VGS} = 20 \rightarrow 0 \ V \end{array} \begin{array}{c} \text{D.U.T.} \\ \text{S} 50 \ \Omega \\ \text{W} \end{array} \begin{array}{c} \text{VDD} \\ \text{W} \end{array}$



TEST CIRCUIT 2 SWITCHING TIME





TEST CIRCUIT 3 GATE CHARGE

TYPICAL CHARACTERISTICS (TA = 25°C)

Figure 1. DERATING FACTOR OF FORWARD BIAS SAFE OPERATING AREA

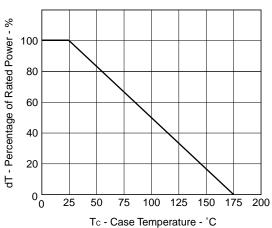


Figure 3. FORWARD BIAS SAFE OPERATING AREA

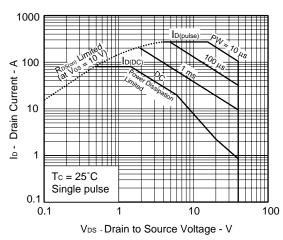


Figure2. TOTAL POWER DISSIPATION vs. CASE TEMPERATURE

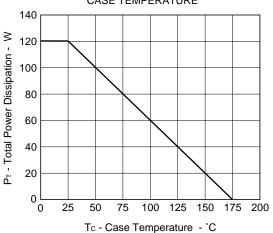


Figure4. SINGLE AVALANCHE ENERGY DERATING FACTOR

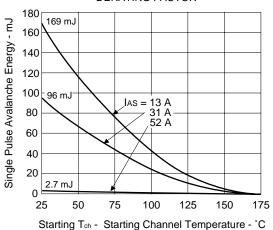
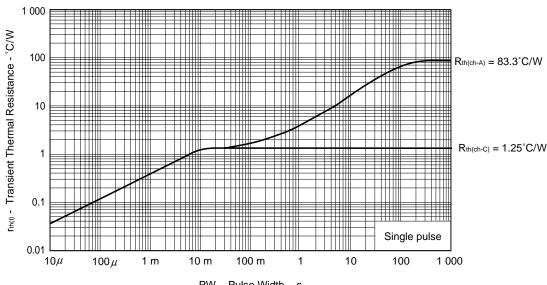


Figure 5. TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH



PW - Pulse Width - s

Figure 6. FORWARD TRANSFER CHARACTERISTICS

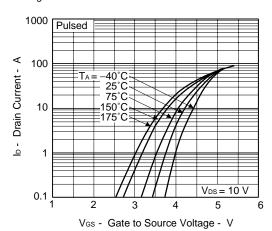


Figure8. FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT

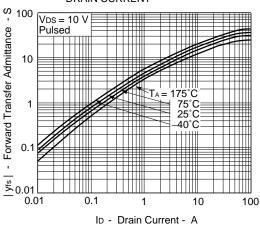


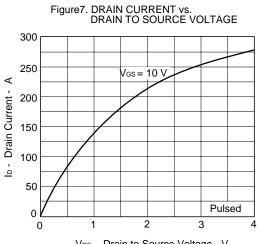
Figure 10. DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT Drain to Source On-state Resistance - mΩ 20 Pulsed 10 Vgs = 10 V

10

ID - Drain Current - A

100

1000



VDS - Drain to Source Voltage - V

Figure9. DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE

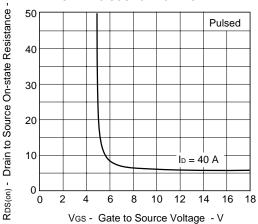
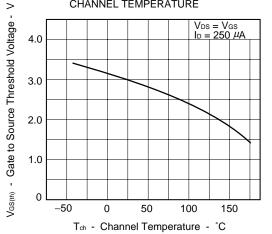


Figure 11. GATE TO SOURCE THRESHOLD VOLTAGE vs. CHANNEL TEMPERATURE



0

Figure 12. DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE

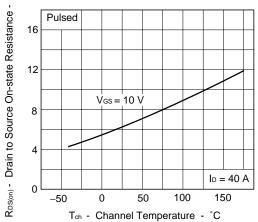


Figure 13. SOURCE TO DRAIN DIODE FORWARD VOLTAGE

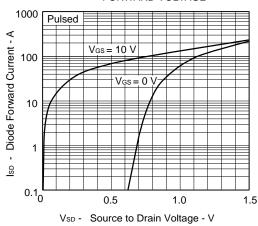


Figure 14. CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE

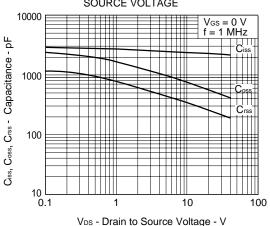


Figure 15. SWITCHING CHARACTERISTICS

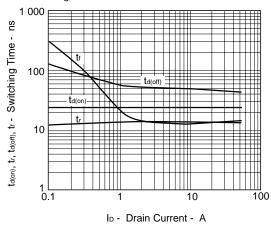


Figure 16. REVERSE RECOVERY TIME vs. DRAIN CURRENT

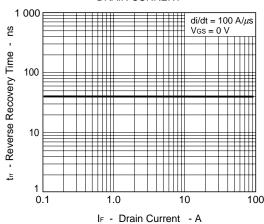
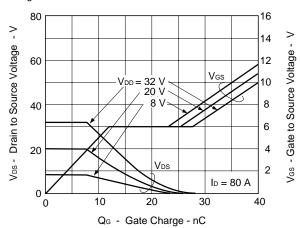
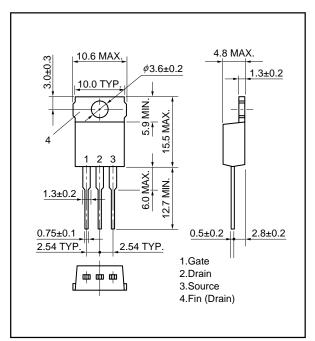


Figure 17. DYNAMIC INPUT/OUTPUT CHARACTERISTICS

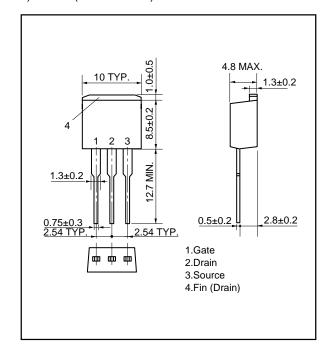


PACKAGE DRAWINGS (Unit: mm)

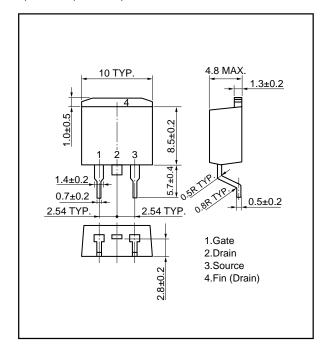
1) TO-220AB (MP-25)



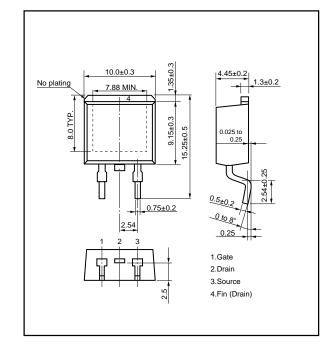
2) TO-262 (MP-25 Fin Cut)



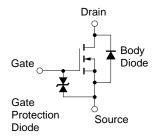
3) TO-263 (MP-25ZJ)



★ 4) TO-263 (MP-25ZK)



EQUIVALENT CIRCUIT



Remark

The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

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